

COMUS

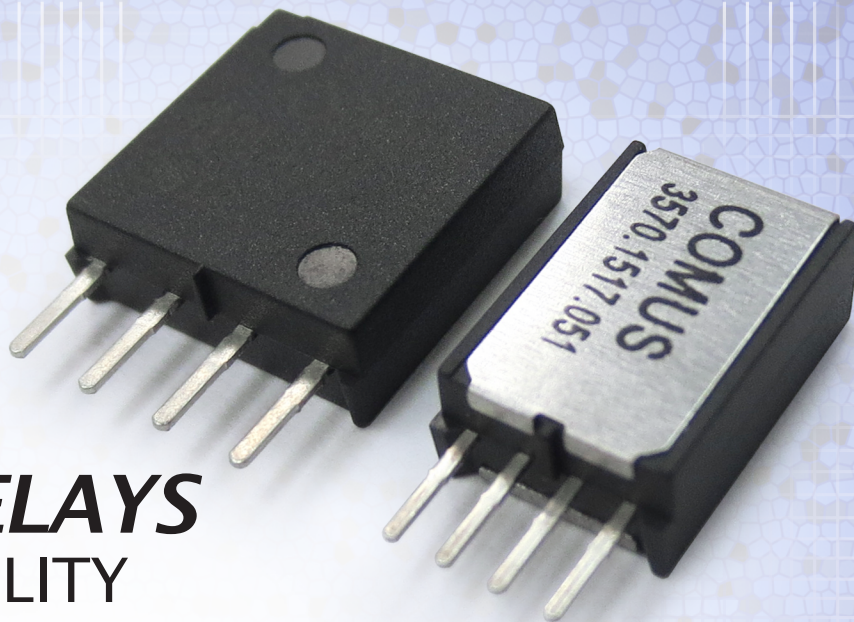


Sensing the world's needs

1517 & 1512 MINI SIP REED RELAYS

DELIVER HIGH RELIABILITY

From the Comus Group of Companies



FEATURES

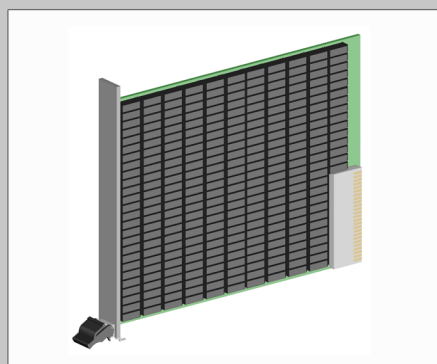
- High-reliability reed switches with sputtered ruthenium contacts for stable contact resistance and long life
- High insulation resistance of minimum 10^{12} Ohms
- Standard magnetic shield to limit magnetic interaction in high-density relay matrices
- Molded thermoset package
- Optional coil suppression diode
- RoHS compliant

We at the Comus Group of Companies are proud to announce the release of the new Comus 1517 Ultra Mini SIP and 1512 Micro Mini SIP series of reed relays. These highly reliable relays are ideal for high-density switching matrices used in Automated Test Equipment (ATE) and data acquisition systems.

The Comus 1517 and 1512 Mini SIP relays use the Comus Technology B.V. (Coto Technology®) reed switches with sputtered ruthenium contacts for high reliability and long life. They feature a magnetic shield to limit magnetic interaction, making them ideal for high-density relay matrices. Also, the 1517 and 1512 series have a PCB footprint up to 75% smaller than industry-standard SIP relays.

The 1517 series offers the same 10 Watts power ratings as the full-size SIP with a 1 Amp carry current and 170 VDC switching voltage. The 1512 series delivers a 50% increase in power rating (15 Watts) compared to standard reed relays.

The [3570.1517](#) and [3570.1512](#) series have a standard lead time of 10 to 12 weeks. The 1517 series' prices start at \$4.00 for 5,000 pieces, while the 1512 series' prices start at \$2.98 for 5000 pieces. Detailed datasheets are available on [Comus' website](#). For further inquiries about these relays, contact Comus Relays and Sensors RI at 401-830-2100 or 401-228-5459.



APPLICATION: High-Density Test Matrix Modules

The small footprint of reed relays with a stable contact resistance is essential for test matrix modules that need to pack as many relays as possible onto a PCB.

When it comes to providing stable contact resistance, experience in manufacturing reed switches with sputtered ruthenium contacts gives Comus an advantage over the competition. The 1517 series also features a 75% smaller PCB footprint than the industry-standard SIP relays, while the 1512 series has a 60% smaller PCB footprint.